

ON Semiconductor®

FGD2736G3-F085

EcoSPARKTM 3 270mJ, 360V, N-Channel Ignition IGBT

Features

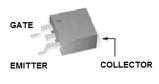
- SCISEnergy = 270mJatT_{.1}=25°C
- SCIS Energy = 170mJ at T_J = 150°C
- Logic Level Gate Drive
- RoHS Compliant



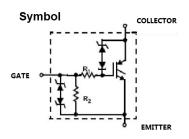
Applications

- Automotive Ignition Coil Driver Circuits
- Coil On Plug Applications

Package



JEDEC TO-252 D-Pak



Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
BV _{CER}	Collector to Emitter Breakdown Voltage (I _C = 1mA)	360	V	
BV _{ECS}	Emitter to Collector Voltage - Reverse Battery Condition ($I_C = 10r$	28	V	
E _{SCIS25}	I_{SCIS} = 13.4A, L = 3.0mHy, R_{GE} = 1K Ω	270	mJ	
E _{SCIS150}	I_{SCIS} = 10.8A, L = 3.0mHy, R_{GE} = 1K Ω	170	mJ	
I _{C25}	Collector Current Continuous, at T _C = 25°C, V _{GE} = 5.0V	21	Α	
I _{C110}	Collector Current Continuous, at T _C = 110°C, V _{GE} = 5.0V	18	Α	
V_{GEM}	Gate to Emitter Voltage Continuous	±10	V	
D.	Power Dissipation Total	T _C = 25°C	150	W
L D	Power Dissipation Derating T _C		1	W/oC
T_J	Operating Junction Temperature Range		-40 to +175	°C
T _{STG}	Storage Junction Temperature Range	-40 to +175	°C	
T _L	Max. Lead Temp. for Soldering (Leads at 1.6mm from case for 10	300	°C	
T _{PKG}	Max Lead Temp for soldering (Package Body for 10s)	260	°C	
ESD	Electrostatic Discharge Voltage at 100 pF, 1500 Ω		4	kV

Thermal Characteristics

$ R_{\theta JC} $ Thermal Resistance Junction to Case $ T_{\theta JC} $

Electrical Characteristics of the IGBT $\rm T_A$ = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
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Off Characteristics

BV _{CER}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_{CE} = 2mA,$ $R_{GE} = 1K\Omega,$ $T_{J} = -40 \text{ to } 150^{\circ}\text{C}$		330	1	390	V
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_{CE} = 10mA,$ $R_{GE} = 0\Omega,$ $T_{J} = -40 \text{ to } 150^{\circ}\text{C}$		350	-	410	٧
BV _{ECS}	Emitter to Collector Breakdown Voltage	$V_{GE} = 0V, I_{CE} = -75mA,$ $T_{J} = 25^{\circ}C$		28	-	-	٧
BV _{GES}	Gate to Emitter Breakdown Voltage	I _{GES} = ±5mA		±11	±14	-	V
1	Collector to Emitter Leakage Current	V_{CE} = 250V, R_{GE} = 1K Ω	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	-	25	μΑ
ICER	Collector to Emitter Leakage Current		$T_{\rm J} = 150^{\rm o}{\rm C}$	-	-	1	mA
	Emitter to Collector Leakage Current	V _{EC} =24V	$T_J = 25^{\circ}C$	-	-	1	mA
I _{ECS}			$T_{\rm J} = 150^{\rm o}{\rm C}$	-	-	40	IIIA
R ₁	Series Gate Resistance		•	-	110	-	Ω
R ₂	Gate to Emitter Resistance			10K	-	30K	Ω

On Characteristics

V _{CE(SAT)}	Collector to Emitter Saturation Voltage	V _{GE} = 4V, I _{CE} = 6A	$T_{J} = 25^{\circ}C$	-	1.25	1.35	V
$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	V _{GE} = 4.5V, I _{CE} = 10A	$T_J = 25^{\circ}C$	-	1.45	1.65	V
$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	V _{GE} = 4.5V, I _{CE} = 1UA	$T_{\rm J} = 150^{\rm o}{\rm C}$		1.6	1.8	V

Dynamic Characteristics

Q _{G(ON)}	Gate Charge	V _{GE} = 5V, V _{CE} = 12V, I _{CE} = 10A		-	18	-	nC
V	Gate to Emitter Threshold Voltage	$I_{CE} = 1 \text{mA}, V_{CE} = V_{GE},$	$T_{J} = 25^{\circ}C$	1.3	1.6	2.2	V
V _{GE(TH)} Gate to Emitter Threshold Volta	Gate to Emitter Threshold Voltage		$T_{J} = 150^{\circ}C$	0.75	1.1	1.8	V
V_{GEP}	Gate to Emitter Plateau Voltage	V_{CE} = 12V, I_{CE} = 10A		-	3.0	-	٧

Switching Characteristics

$t_{d(ON)R}$	Current Turn-On Delay Time-Resistive	V_{CE} = 14V, R_L = 1 Ω	-	0.9	4	μS
t_{rR}	Current Rise Time-Resistive	$V_{GE} = 5V, R_G = 1K\Omega$	-	3	7	μS
t _{d(OFF)L}	Current Turn-Off Delay Time-Inductive	V _{CE} = 300V, L = 2mH,	-	4.4	15	μS
t_{fL}	Current Fall Time-Inductive	$V_{GE} = 5V, R_G = 1K\Omega$	-	1.9	15	μS

Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FGD2736G3	FGD2736G3-F085	TO-252AA	330mm	16mm	2500units

Typical Performance Curves

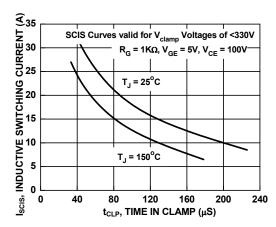


Figure 1. Self Clamped Inductive Switching Current vs. Time in Clamp

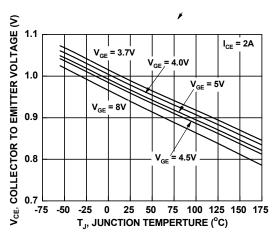


Figure 3. Collector to Emitter On-State Voltage vs. Junction Temperature

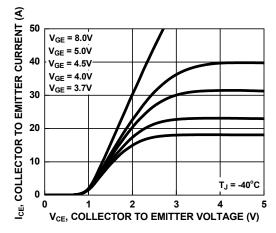


Figure 5. Collector to Emitter On-State Voltage vs. Collector Current

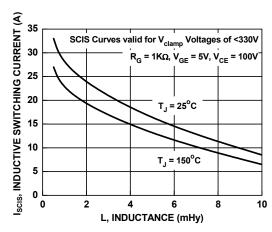


Figure 2. Self Clamped Inductive Switching Current vs. Inductance

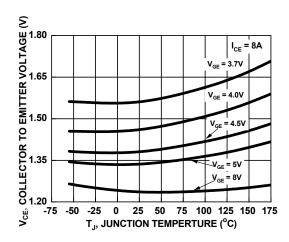


Figure 4. Collector to Emitter On-State Voltage vs. Junction Temperature

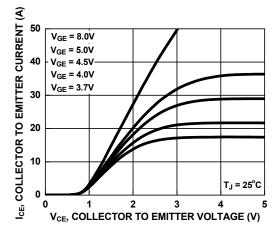


Figure 6. Collector to Emitter On-State Voltage vs. Collector Current

Typical Performance Curves (Continued)

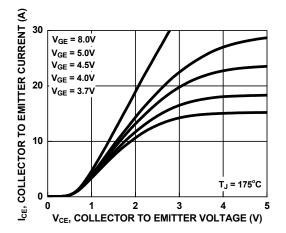
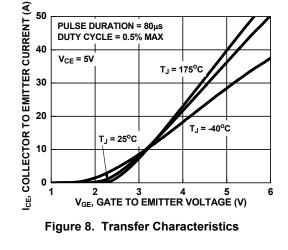


Figure 7. Collector to Emitter On-State Voltage vs. Collector Current



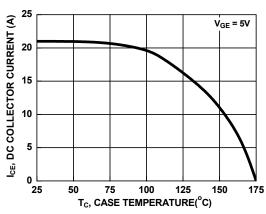


Figure 9. DC Collector Current vs. Case Temperature

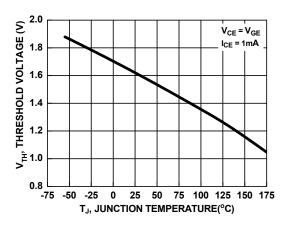


Figure 10. Threshold Voltage vs. Junction Temperature

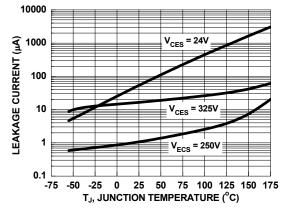


Figure 11. Leakage Current vs. Junction Temperature

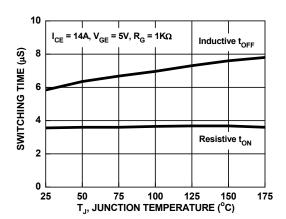


Figure 12. Switching Time vs. Junction Temperature

Typical Performance Curves (Continued)

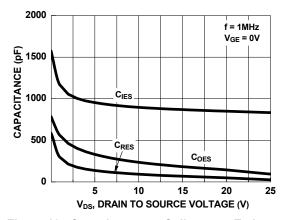


Figure 13. Capacitance vs. Collector to Emitter Voltage

Figure 14. Gate Charge

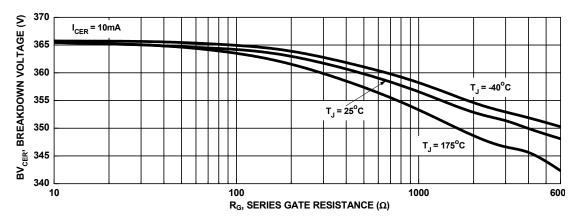


Figure 15. Break down Voltage vs. Series Gate Resistance

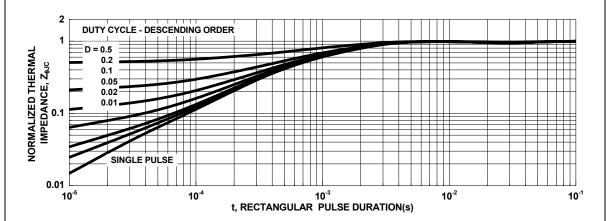


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

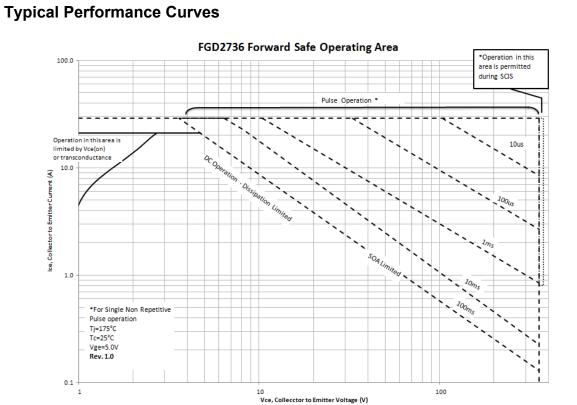
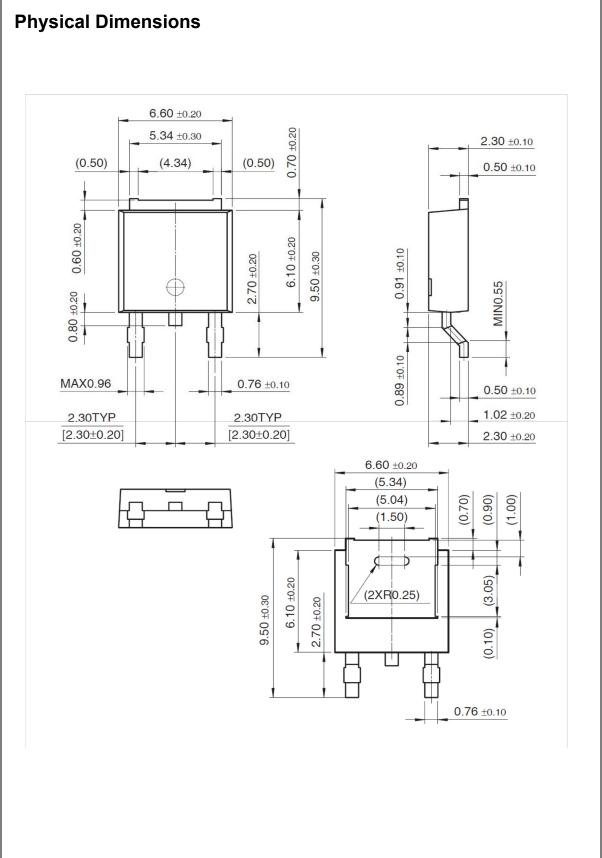


Figure 17. Forward Safe Operating Area



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